

Accurate Modeling of the Self-Heating and Trapping Effects in GaN HEMTs

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Keysight Technologies

Outline

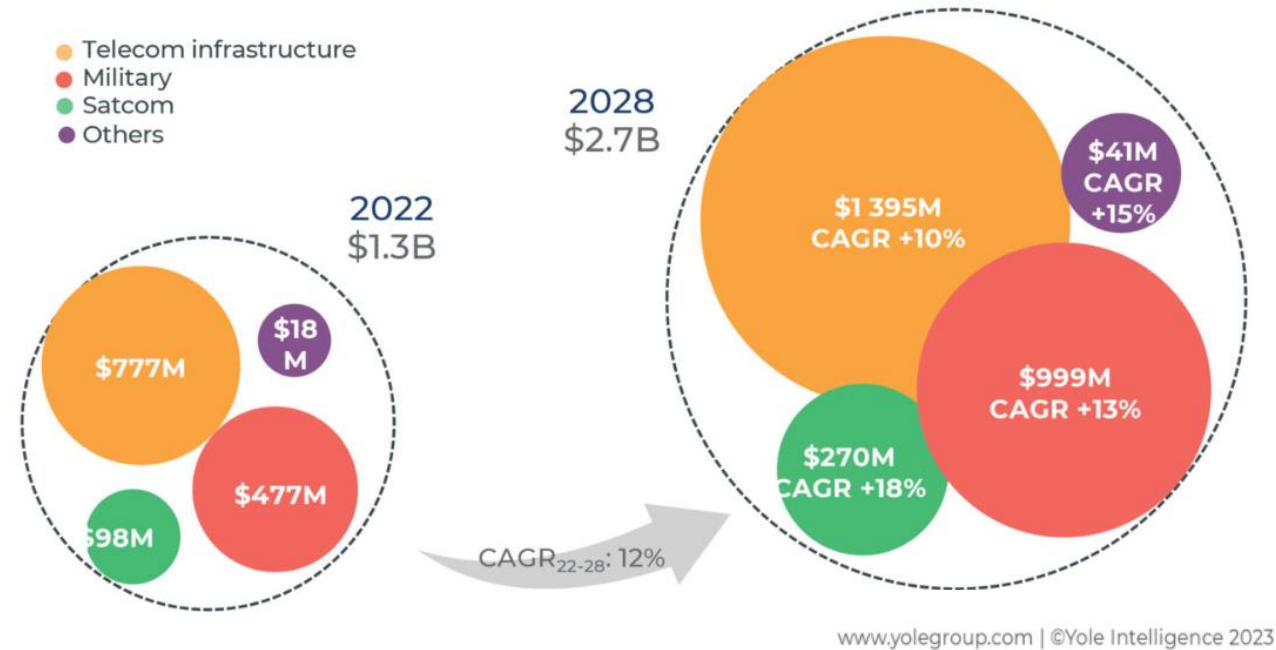
- **Introduction of GaN HEMTs modeling and new features in ASM-HEMT 101.4 and MVSG_CMC 3.2.0**
- RF parameter extraction package in IC-CAP
 - Parameter extraction flow
 - Thermal extraction
 - Trapping extraction
- Summary

RF GaN is Hot

- RF GaN market will grow from \$1.3B to \$2.7B by 2028

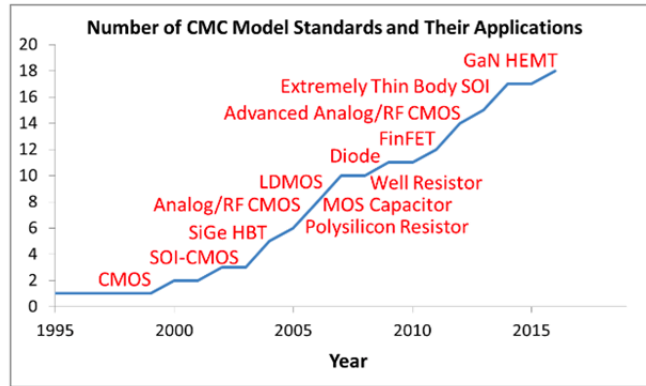
2022-2028 RF GAN DEVICE MARKET FORECAST

Source: RF GaN 2023 report, Yole Intelligence, 2023



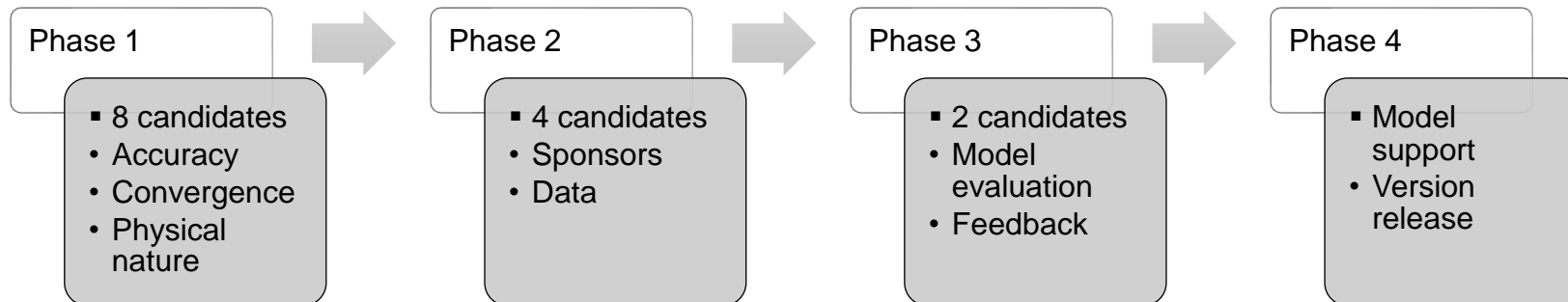
Source: "RF GaN market broadens its appeal with an appetite for GaN-on-Silicon" - www.yolegroup.com

GaN Model Development History



ASM-HEMT 101.4

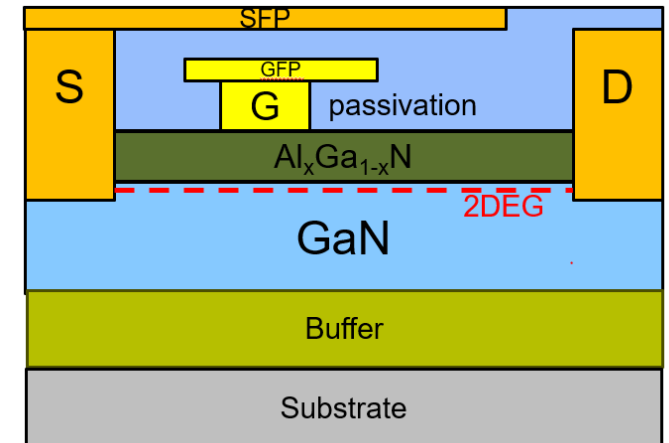
MVSG_CMC 3.2.0



Source: "RF GaN market broadens its appeal with an appetite for GaN-on-Silicon" - www.yolegroup.com

Modeling of Various GaN Device Effects

- **Field-plates** – modeled with computationally efficient formulation
- **Non-linear access region** – physics-based formulation covering linear and saturation
- **Gate-current (IG)** – physics-based formulations covering multiple IG mechanisms
- **Trapping effects** – multiple modes to suit applications and extraction flows
- **Noise** – Physics-based thermal- and flicker noise models
- **Self-heating effect** – modeled with thermal sub-circuits
- **Ambient temperature effects** – modeled with temperature-dependent formulations
- ...



All effects modeled with consistency with each-other

Source: Sourabh Khandelwal, "Scalable nonlinear RF modeling of GaN HEMTs with industry standard ASM-HEMT compact model - Enabling new modeling capabilities for GaN" - IMS

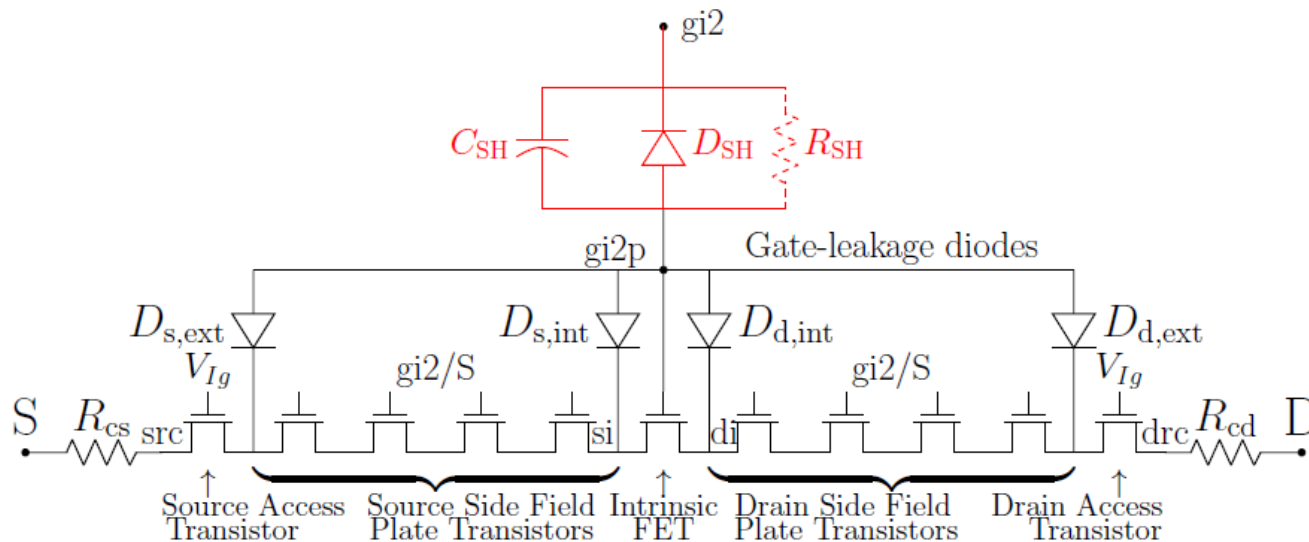
ASM-HEMT 101.4 New Features

- New current saturation formulation added to the access region resistance model
- Two new model parameters t_{epi} and a_{sub} added to tune the substrate voltage dependence of pinch-off voltage
- Technical manual updated with new section 5.2 describing statical model extraction flow

Source: Release notes of ASM-HEMT 101.4

MVSG_CMC 3.2.0 New Features

- External thermal node added – additional temperature offset can be defined at the netlist level
- Schottky p-GaN implementation to include dynamic V_t effect

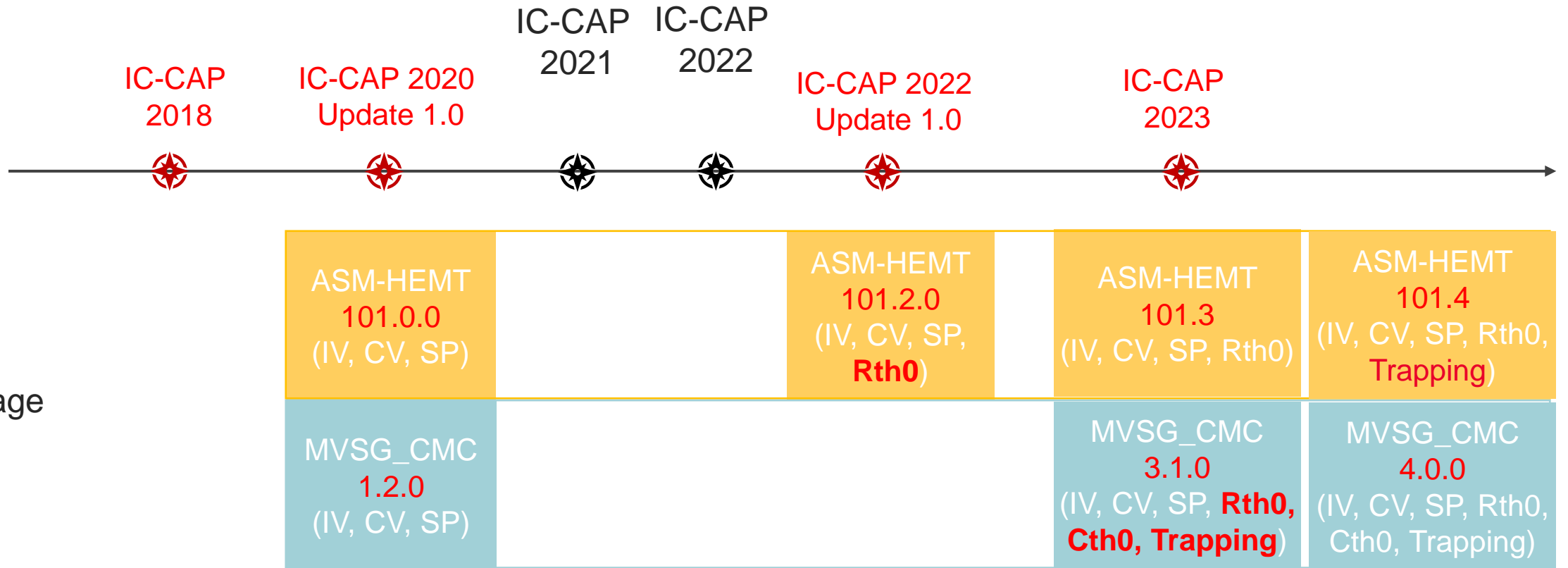


Source: release notes of MVSG_CMC 3.2.0

Outline

- Introduction of GaN HEMTs modeling and new features in ASM-HEMT 101.4 and MVSG_CMC 3.2.0
- **RF parameter extraction package in IC-CAP**
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ASM and MVSG Modeling Packages Updates in IC-CAP



RF package

Modeling Flow (ASM-HEMT)

DUTs-Setups **Circuit** Model Par

+ [] [] []

DeviceA_5053_8x100

INITIALIZE

- README_FIRST
- LOAD_MEAS_DATA
- PROJECT_NAMING
- DEFINE_WORK_DIR
- INIT_MODELING

Load Meas Data/Setup environment/Model Parameter initialization

CONTACT_RESISTANCES

- DC_Meas_R_Port1
- DC_Meas_R_Port2

Contact resistance from the probe

DC_MODELING_vt_u0

- id_vgs_Transfer_lin

CV_Modeling_init

- spar_cap_vg_vd1

Initial threshold voltage and mobility

Extract cap by using S-parameters

R_L_Subcircuit

- Spar_bias
- Spar_sub

Extract parasitics using S11 and S22

DC_RTH_MODELING

- idvd_Output_25C

DC_PULSED_RTH_MODELING

- idvd_vg0V0_vd0V0_100C
- idvd_vg0V0_vd0V0_125C
- idvd_vg0V0_vd0V0_150C
- idvd_vg0V0_vd0V0_175C

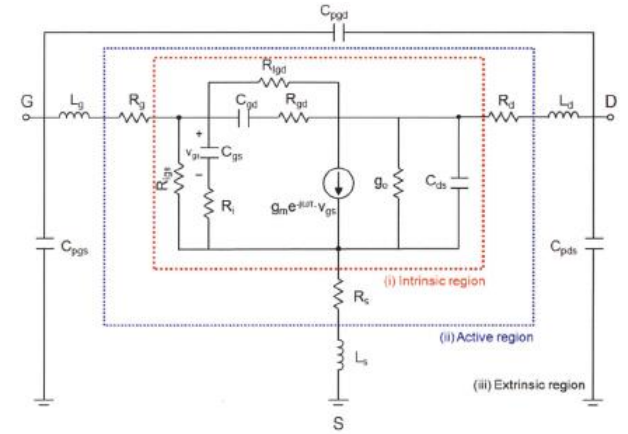
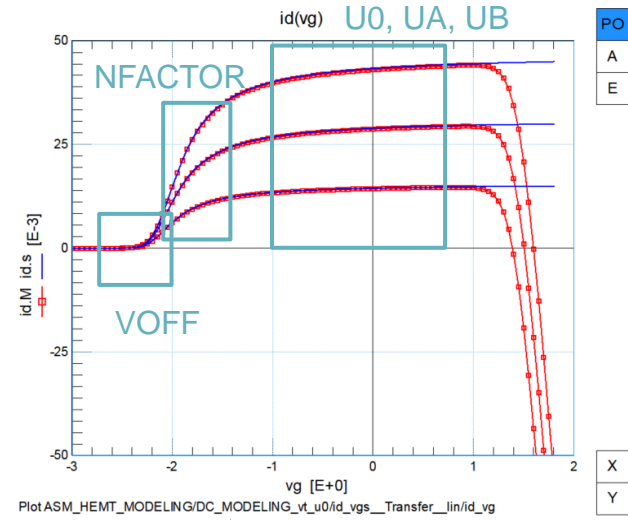
Self-heating extraction with static and pulsed IV

Initialization

Contact resistance

DC&CV init

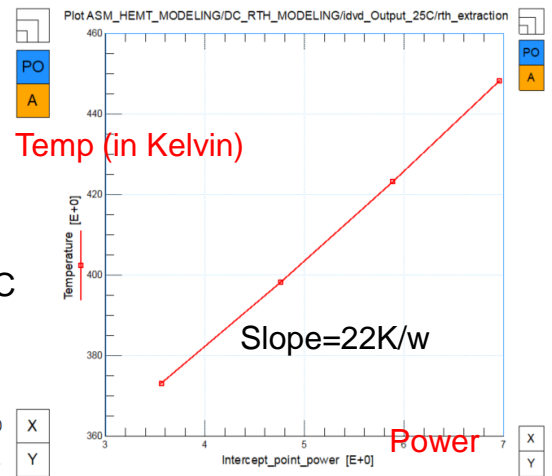
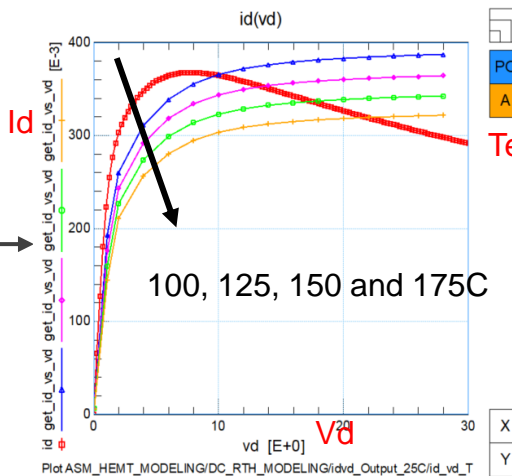
Thermal modeling



$$C_{gs} = \frac{Im(Y_{11}) + Im(Y_{12})}{\omega} \left[1 + \left(\frac{Re(Y_{11}) + Re(Y_{12}) - g_{lgs}}{Im(Y_{11}) + Im(Y_{12})} \right)^2 \right]$$

$$C_{gd} = -\frac{Im(Y_{12})}{\omega} \left[1 + \left(\frac{Re(Y_{12}) + g_{lgs}}{Im(Y_{12})} \right)^2 \right]$$

$$C_{ds} = \frac{Im(Y_{22}) + Im(Y_{12})}{\omega}$$



Extraction flow

Modeling Flow (ASM-HEMT)

Extraction flow

- Continues IV for DC modeling & Temperatures

 - DC_MODELING
 - ig_vgs_Input
 - id_vgs_Transfer_lin
 - id_vgs_Transfer_subVOFF
 - id_vgs_Transfer
 - id_vds_Output
 - DC_MODELING_TEMP
 - id_vds_Output_m25C
 - id_vds_Output_25C
 - id_vds_Output_75C
 - id_vds_Output_100C
- CV modeling

 - CV_Modeling
 - spar_cap_vd_vg_low
 - spar_cap_vg_vd1
 - spar_cap_vd_vg_T
 - spar_cap_vg_vd_high
 - DC_MODELING_LSYNC
 - DC_PULSED
 - DC_ModelRobustness
- S-parameters

 - SPAR_MODELING
 - Init_Spar_Modeling
 - vg_1st_sweep_vd_2nd
 - vd_1st_sweep_vg_2nd
 - Spar_all_freq_biases
 - Spar_bias_point
 - ModelQuality_Verification
- Trapping modeling

 - TRAPPING_MODELING
 - pulsed_vd_50
 - pulsed_vd_40

Extract DC parameters and RTH0

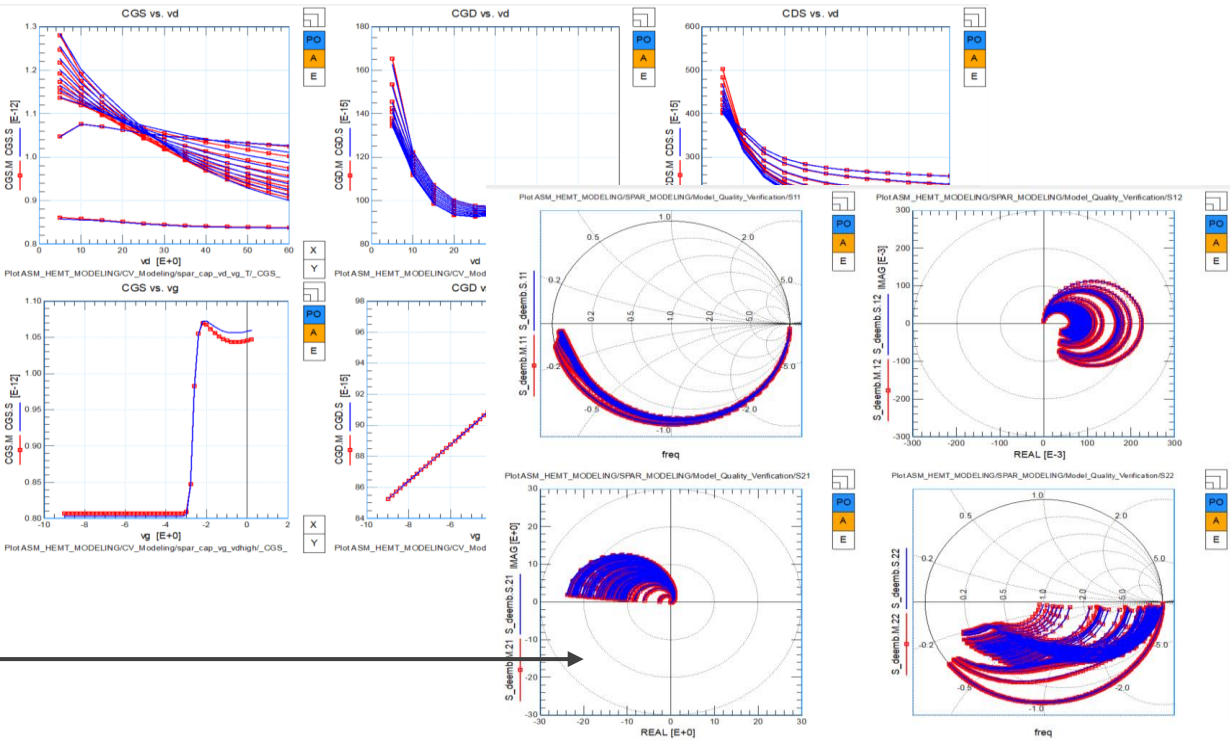
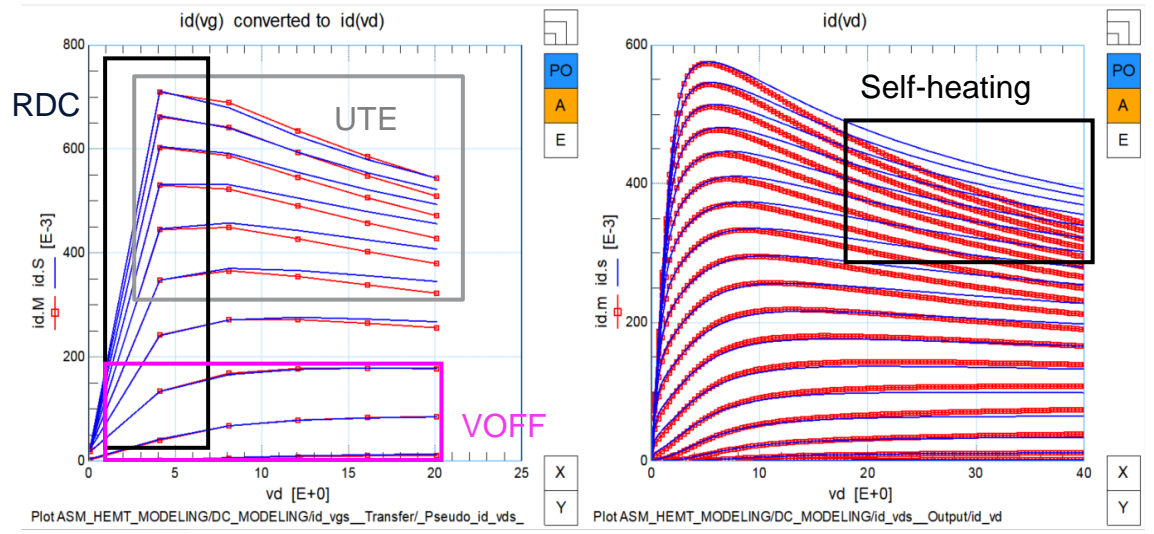
Extract thermal parameters with IdVd at different temperatures

Extract cap parameters at low voltage and thermal parameters at high voltage

Extract parasitic effect (LG, LD, LS, RG)

Gate-lag and drain-lag

U0, UA, RDC



MVSG_CMC Parameter Extraction in IC-CAP

Contact Resistances

Capacitance vs. Voltage

Pulsed IV for DC

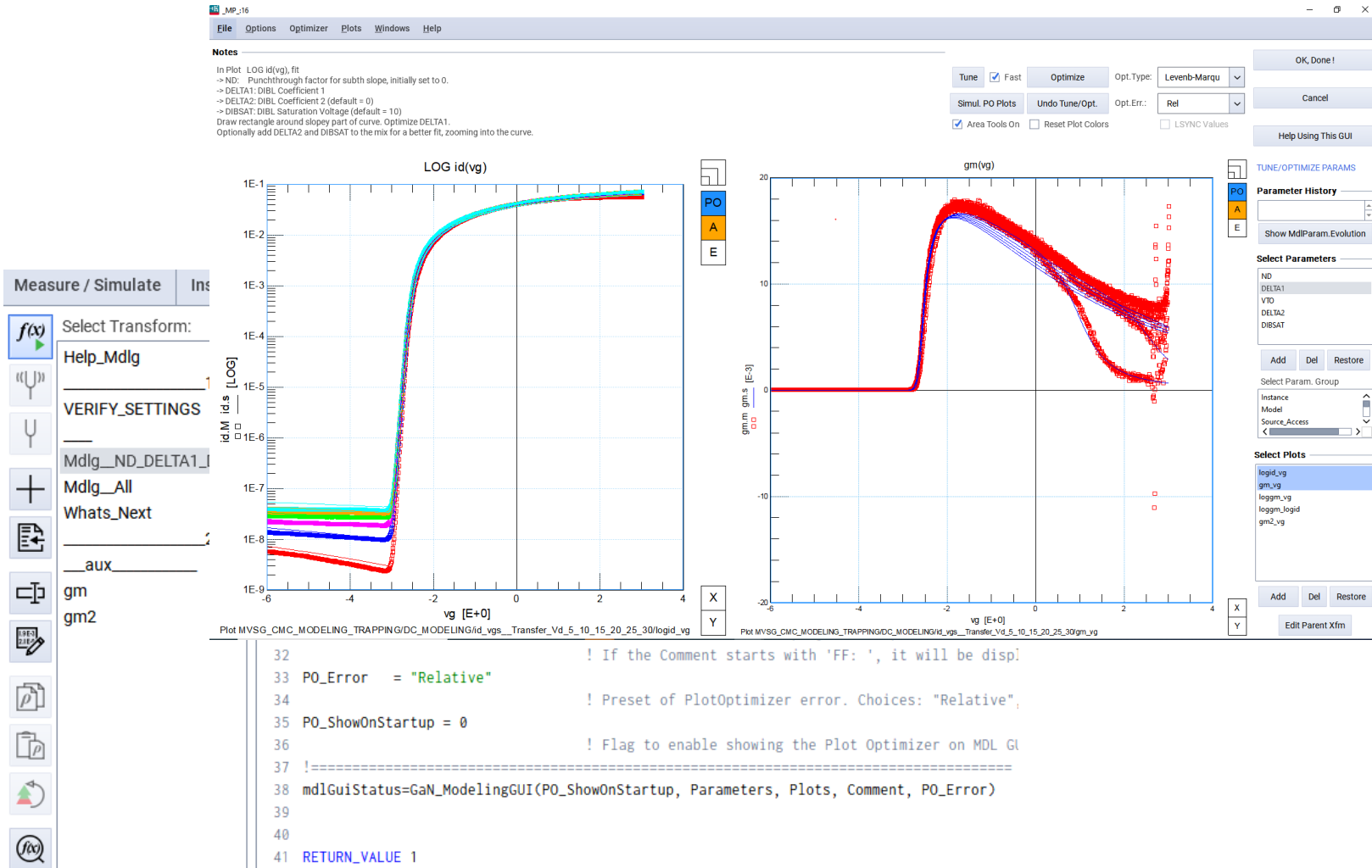
Thermal Sub Circuit

S-Parameters

Trapping Module

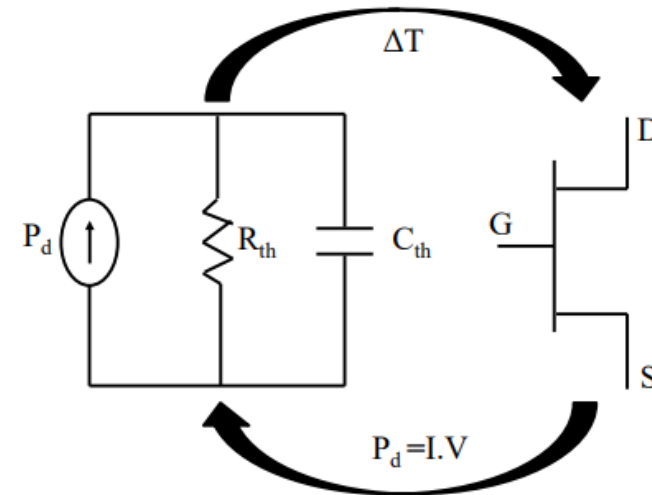
Large Signal Power

UTILITIES: provide GUI and function to help modeling



Self-Heating Effect

- Self-heating effect has become a greater concern for industry in recent years. Since smaller devices, new materials and geometries, resulting in an increase of this effect.
- Self-heating results in an increase of the device temperature will cause mobility reduction, compromised reliability and signal delays.
- In ASM-HEMT and MVSG_CMC models, self-heating effect is modeled by standard R-C network, which contains thermal resistance R_{th} and thermal capacitance C_{th} .

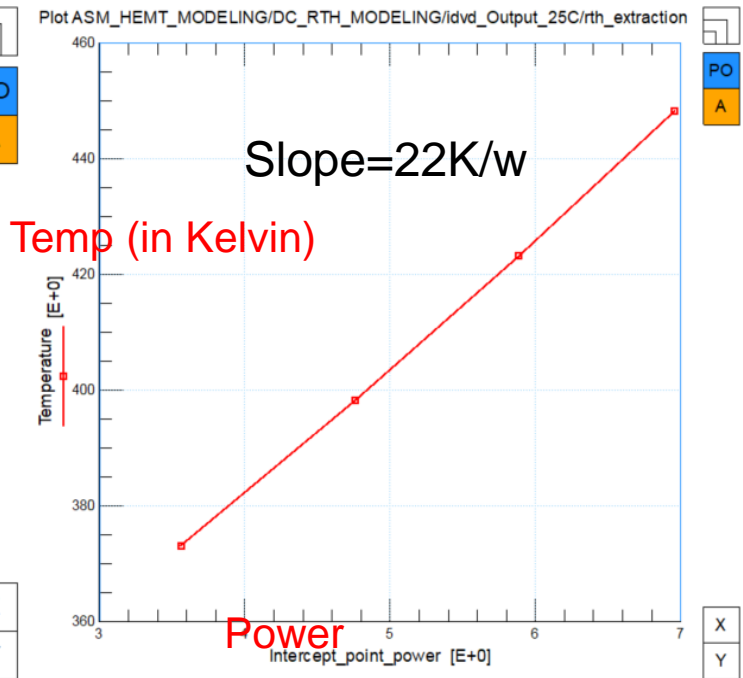
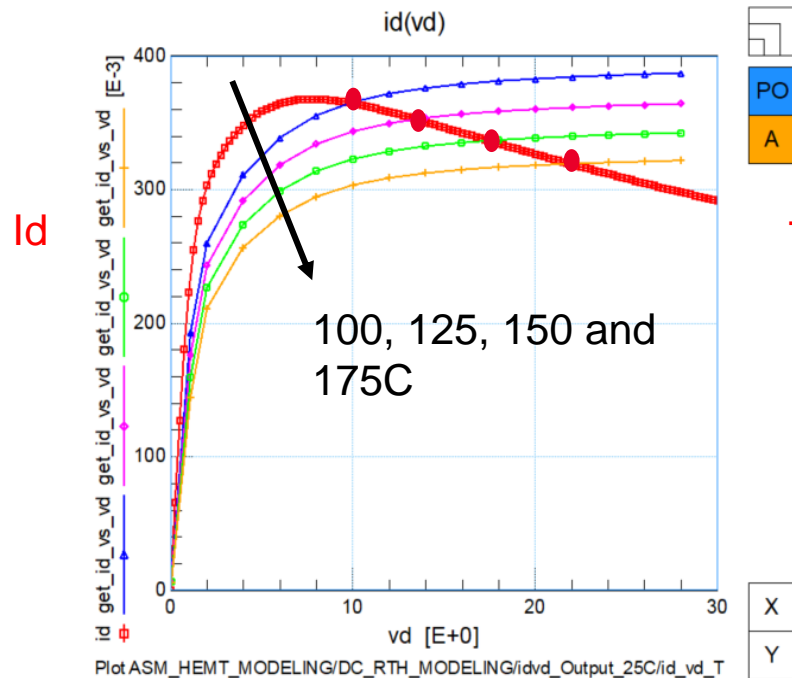


Source: S. Khandelwal et al., "ASM-HEMT 101.2.0 Advanced SPICE Model for HEMTs," Technical Manual [2020].

Self-heating Extraction

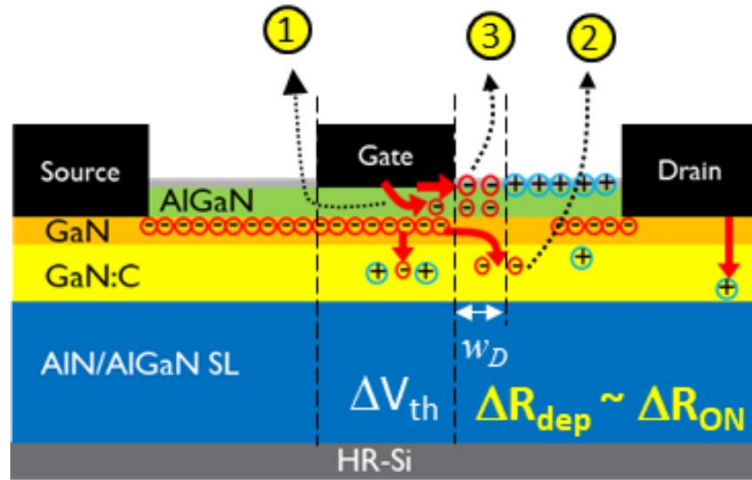
- We need two types of data:
 - Static IdVd at room temperature.
 - Pulsed IdVd at various other than the room temperature.
 - Vd0=0V and Vg0=0V, which are the voltage at low level.

DC, T1=25C
 Pulsed from (0,0), T2=100C
 DC curve: $T1 = T1_{ambient} + RTH0 \cdot P_{diss1}$
 Pulsed curve: $T2 = T2_{ambient} + RTH0 \cdot P_{diss2}$
 ~~$RTH0 = (T1_{ambient} - T2_{ambient}) / P_{diss1}$~~



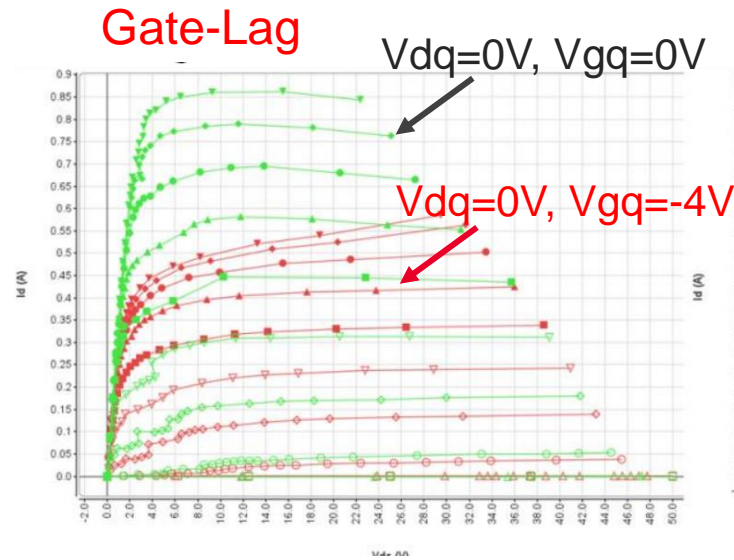
Trapping Effect

Introduction of Trapping Effect



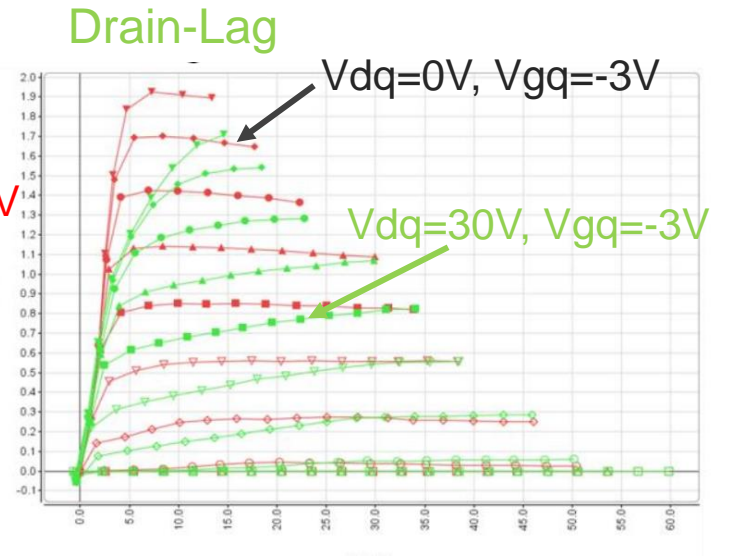
Charge trapping in the buffer layer and AlGaN/GaN interface layer cause a reduction in 2DEG channel charge density, causing a modulation of drain current I_D .

The trap model accurately captures Dynamic- R_{ON} and knee walkout.



Gate-lag

- $V_{dq} = 0V$
- $V_{gq} = \text{Deep OFF condition}$: A strong field through the AlGaN layer. No field through buffer (since $V_{ds} = 0$). Only surface traps activated.

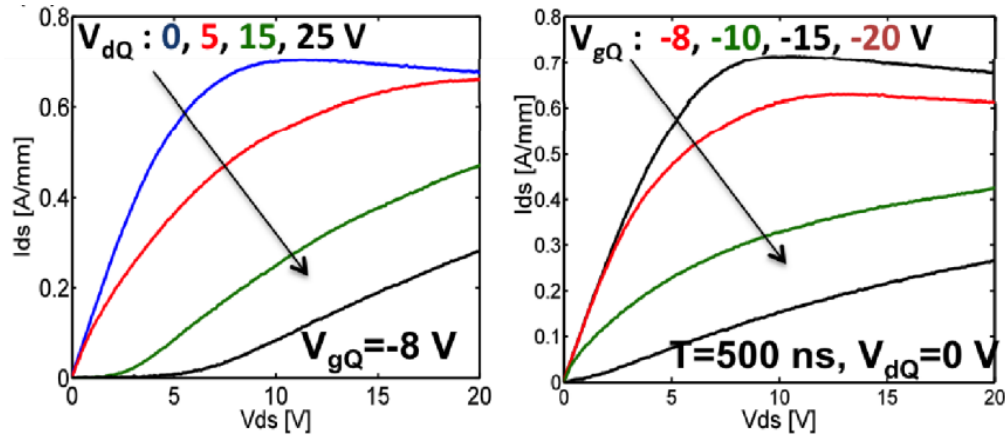


Drain-lag

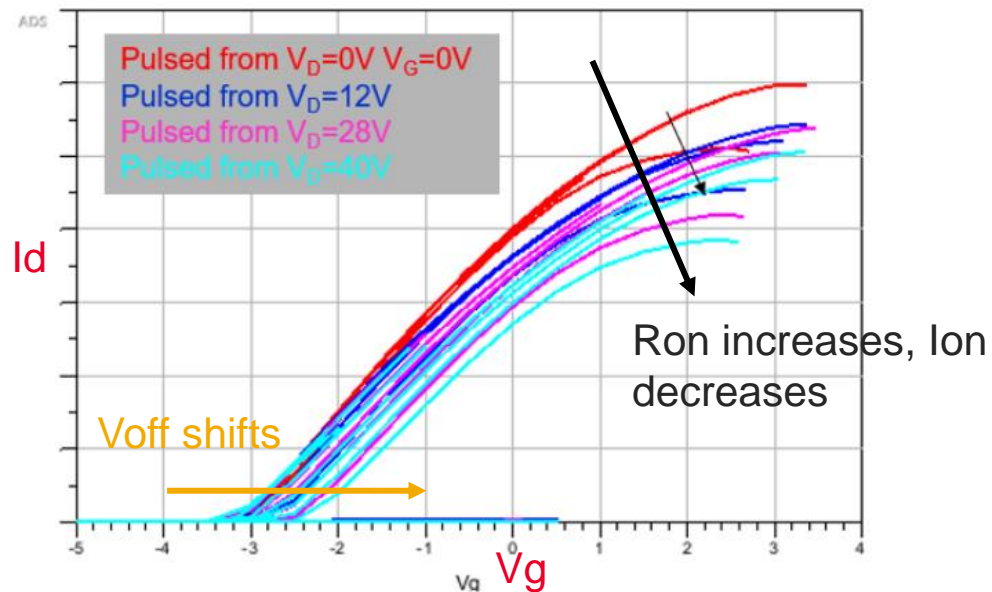
- $V_{dq} = \text{A significantly positive voltage}$
- $V_{gq} = \text{Deep OFF condition}$: A strong field through the AlGaN layer as well as the buffer. Both surface and buffer traps activated.

Source: R. Fang, D. Ma, U. Radhakrishna, and L. Wei, "MMSG GaN-HEMT Model: Approach to Simulate Fringing Field Capacitances, Gate Current De-biasing, and Charge Trapping Effects," accepted by 2022 IEEE BiCMOS and Compound Semiconductor Integrated Circuits and Technology Symposium

Pulsed IV Measurements



- Decrease of I_{on} , increase of R_{on} and V_{dsat}
- After voltage stress is removed, a non-negligible time is required for the 2DEG to regain charge.
- Critical for circuit dynamic operations for RF.



- Increase of R_{on} and cut-off voltage

Source: U. Radhakrishna, D. Piedra, Y. Zhang, T. Palacios and D. Antoniadis, "High voltage GaN HEMT compact model: Experimental verification, field plate optimization and charge trapping," 2013 IEEE International Electron Devices Meeting, Washington,

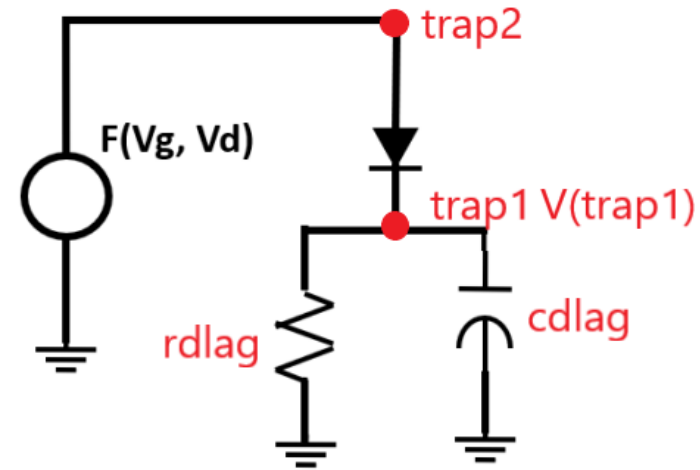
U. Radhakrishna and L. Wei, "MIT virtual source GaN HEMT: MVSG model manual," May 1 2022

Trapping Extraction

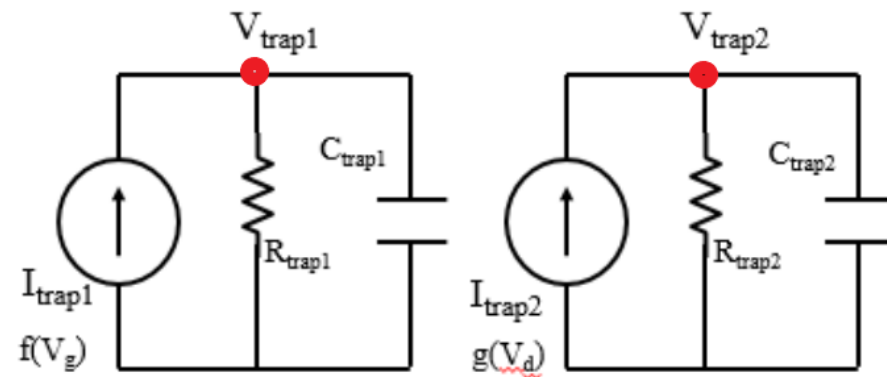
ASM-HEMT Trapping Model 1 and 2

- TRAPMOD=0
Trapping model turns off
- TRAPMOD=1
 - A single RC sub-circuit
 - Trap voltage $V(\text{trap1})$ will feed back into model
 - $voff_cap$, $eta0_cap$, rs_cap , rd_cap changing due to the trapping
- TRAPMOD=2
 - Two RC sub-circuits are used
 - V_{trap1} and V_{trap2} will feed back into model
 - $Voff_trap$, ron_trap , $cdscd_trap$, $eta0_trap$ changing due to the trapping

TRAPMOD=1



TRAPMOD=2



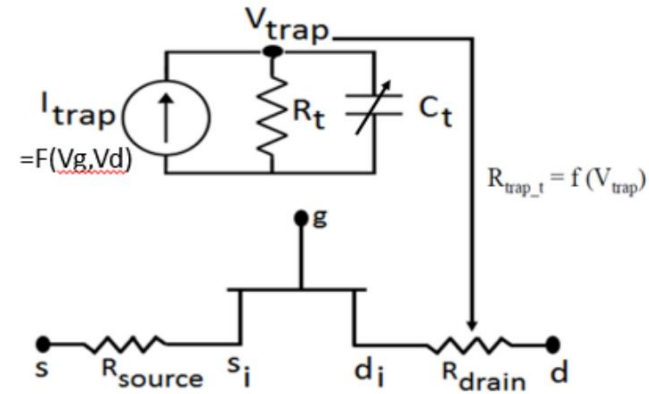
Source: S. Khandelwal, J. Hodges, and N. Reddy, ASM-HEMT 101.3.0 Advanced SPICE Model for HEMTs Technical Manual, Macquarie University

Trapping Extraction

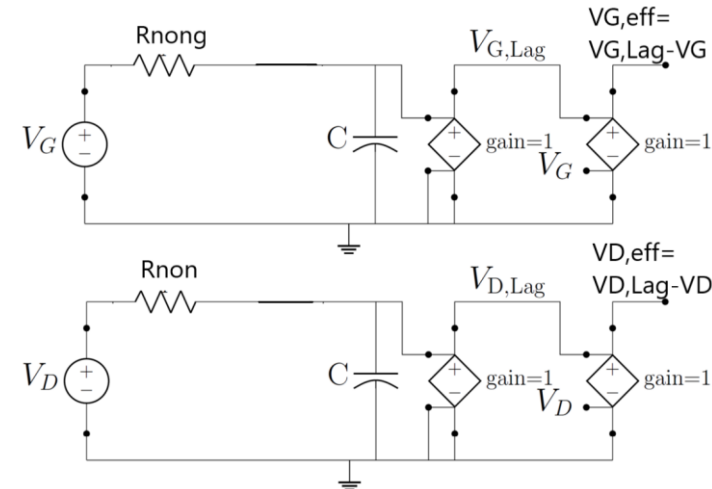
ASM-HEMT Trapping Model 3 and 4

- TRAPMOD=3
 - Single RC sub-circuit
 - Recommended for GaN power device dynamic ON-resistance
 - Only **drain-side resistance** is affected
- **TRAPMOD=4**
 - Two RC sub-circuits are used
 - Model drain-lag and gate-lag with most flexibility
 - **voffglag, u0glag, vsatglag** changing due to gate-lag ($V_{G,eff}$)
 - **voffdlag, ns0sdlag, ns0ddlag** changing due to drain-lag ($V_{D,eff}$)

TRAPMOD=3



TRAPMOD=4



Trapping Extraction

MVSG_CMC Charge Trapping Model

- TRAPSELECT=0

Trapping model turns off

- TRAPSELECT=1

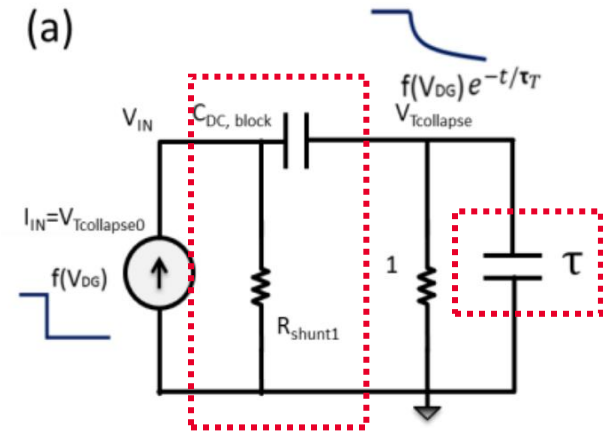
A single RC network with a constant time τ is used for modeling trapping and de-trapping constant time.

- **TRAPSELECT=2 (new)**

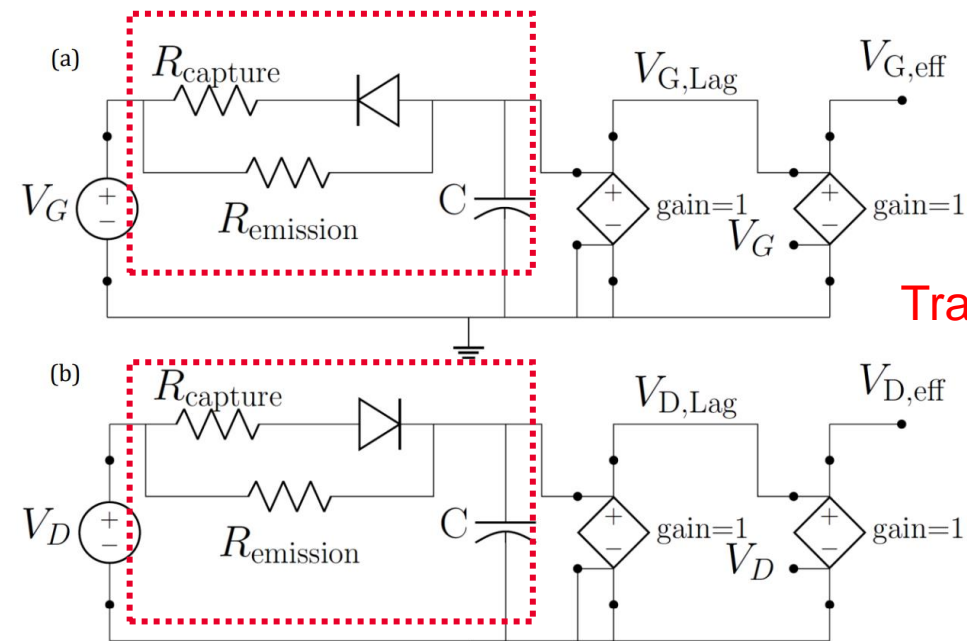
Two parallel R-branches in an RC network with an ideal series diode on one of the resistance branches.

Two-time constants are used.

Recommended due to more flexibility



Trapping model 1



Trapping model 2

$$\tau_{capture} \approx R_{capture}C \text{ in forward-biased}$$

$$\tau_{emission} \approx R_{emission}C \text{ in reverse-biased}$$

Source: R. Fang, D. Ma, U. Radhakrishna, and L. Wei, "MVSG GaN-HEMT Model: Approach to Simulate Fringing Field Capacitances, Gate Current De-biasing, and Charge Trapping Effects," accepted by 2022 IEEE BiCMOS and Compound Semiconductor Integrated Circuits and Technology Symposium

Trapping Extraction (ASM-HEMT)

Gate Lag Trapping Extraction

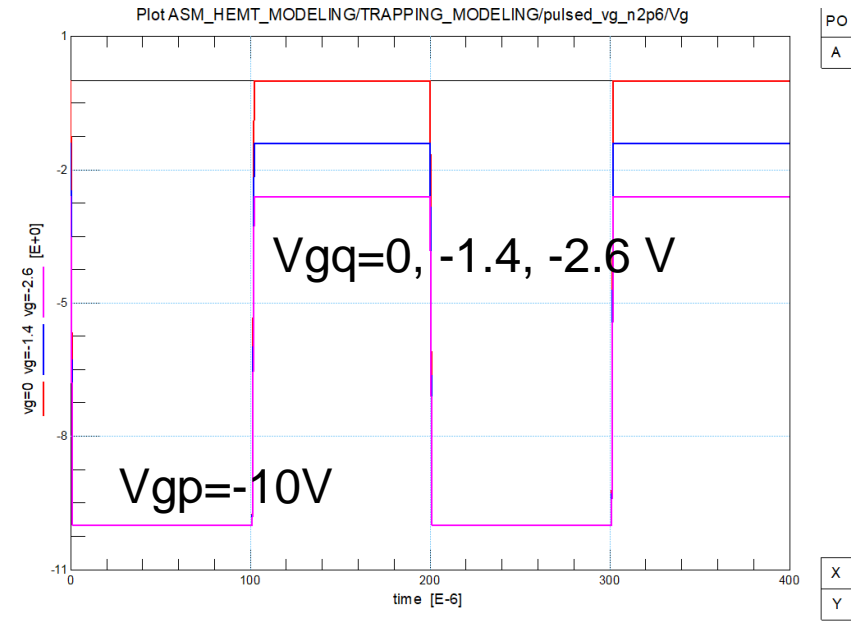
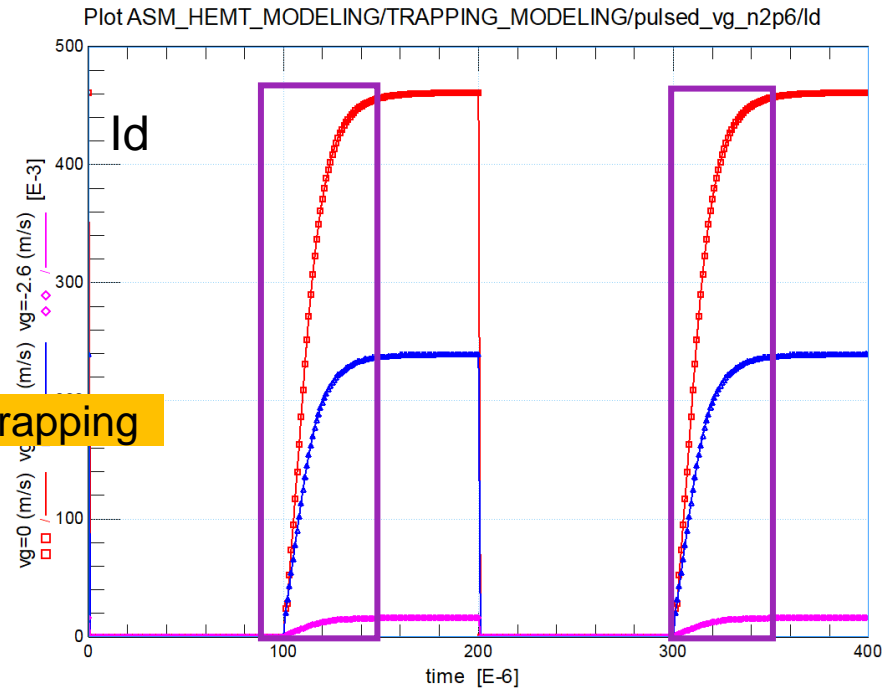
DUTs-Setups Circuit Model Pa



- _____3
- > DC_RTH_MODELING
- > DC_PULSED_RTH_MODELING
- _____4
- > DC_MODELING
- > DC_MODELING_TEMP
- _____5
- > CV_Modeling
- _____6
- > DC_MODELING_LSYNC
- > DC_PULSED
- > DC_ModelRobustness
- _____7
- > SPAR_MODELING
- > SPAR_MODELING_LSYNC
- _____8
- > TRAPPING_MODELING
 - pulsed_vg_0
 - pulsed_vg_n1p4
 - pulsed_vg_n2p6
 - pulsed_vd_50
 - pulsed_vd_40
 - pulsed_vd_30
 - pulsed_vd_20
 - pulsed_vd_10
- _____9
- > FINISH_MDLG

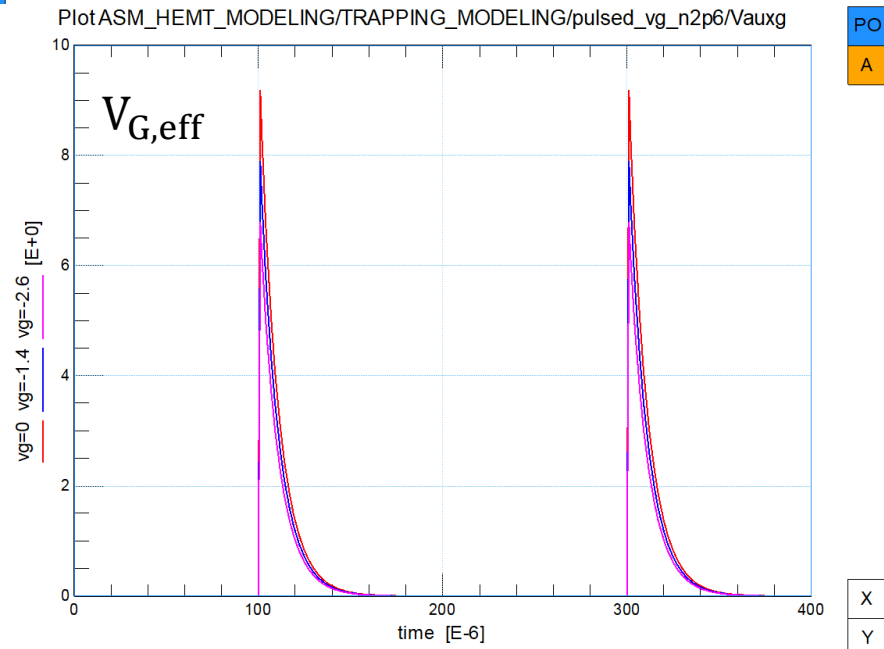
Gate-Lag trapping

- TRAPMOD=4 is used
- Gate-lag-related parameters can be tuned.
- **voffglag, u0glag, vsatglag** related trapping parameters



PO
A

X
Y



PO
A

X
Y

PO
A

X
Y

Trapping Extraction (ASM-HEMT)

Drain Lag Trapping Extraction

DUTs-Setups Circuit Model Pa

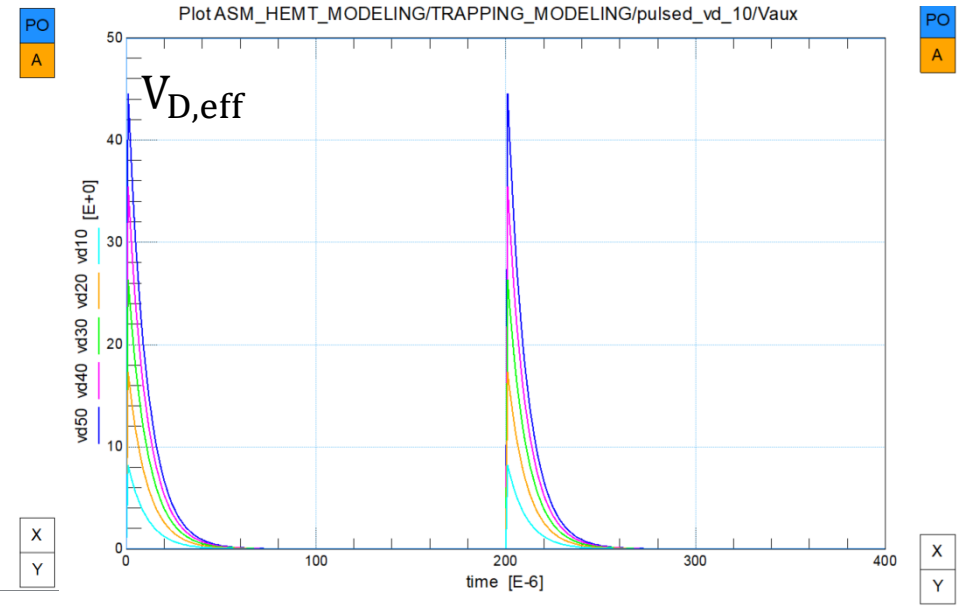
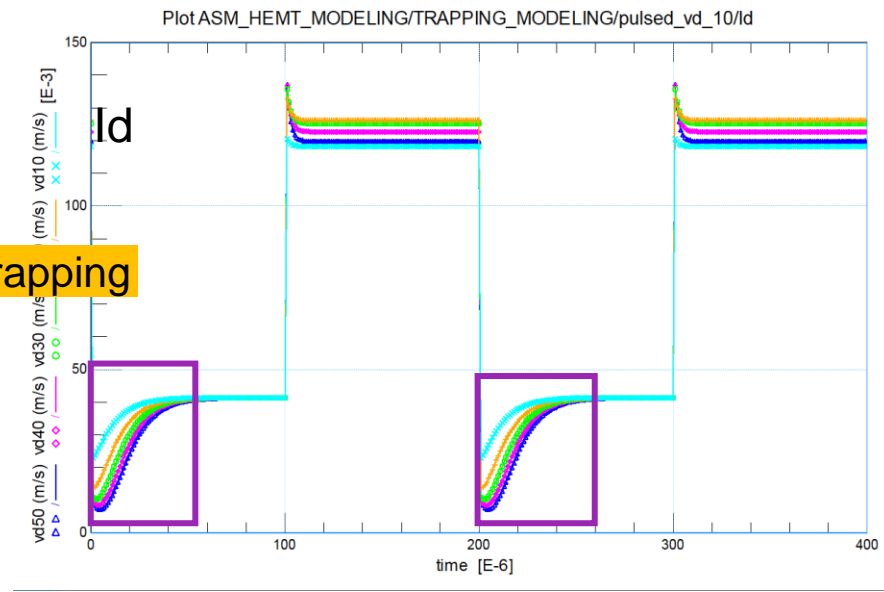
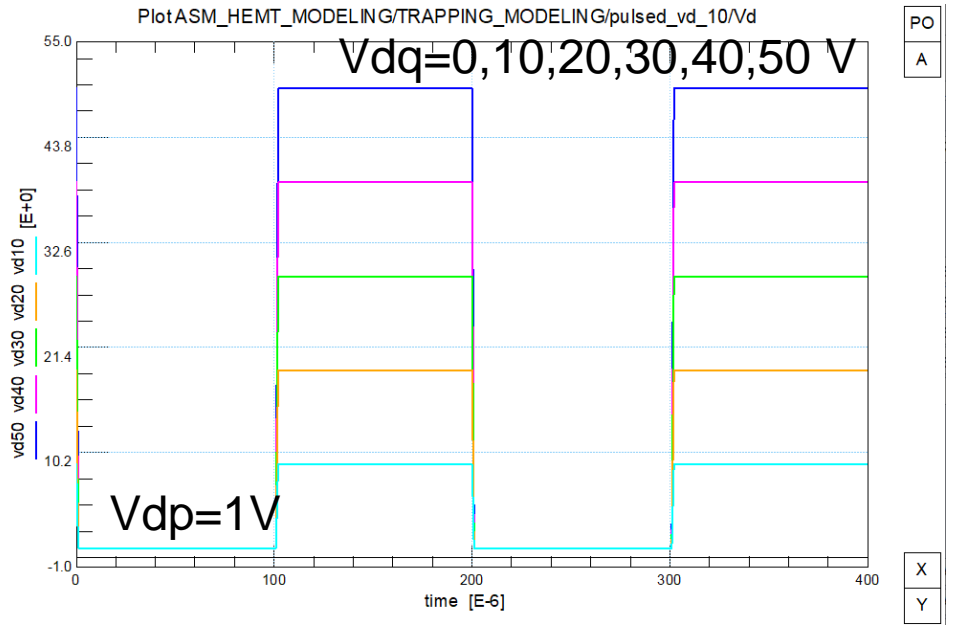


- _____3
- > DC_RTH_MODELING
- > DC_PULSED_RTH_MODELING
- _____4
- > DC_MODELING
- > DC_MODELING_TEMP
- _____5
- > CV_Modeling
- _____6
- > DC_MODELING_L_SYNC
- > DC_PULSED
- > DC_ModelRobustness
- _____7
- > SPAR_MODELING
- > SPAR_MODELING_L_SYNC
- _____8
- > TRAPPING_MODELING
 - pulsed_vg_0
 - pulsed_vg_n1p4
 - pulsed_vg_n2p6
 - pulsed_vd_50**
 - pulsed_vd_40**
 - pulsed_vd_30**
 - pulsed_vd_20**
 - pulsed_vd_10**
- _____9
- > FINISH_MDLG

- TRAPMOD=4 is used
- Drain-lag-related parameters can be tuned.
- **voffdlag, ns0sdlag, ns0ddlag** related trapping parameters

Drain-Lag trapping

Extraction flow



Summary

- The latest version of ASM-HEMT 101.4 and MVSG_CMC 3.2.0 is implemented in ADS 2024 update 1
- The RF package with ASM-HEMT 101.3 and MVSG_CMC 3.1.0 is implemented in IC-CAP 2023 and newer version
- Both ASM-HEMT and MVSG_CMC have good performance on GaN HEMTs modeling:
 - Core model for DC
 - CV and S-parameters
 - Thermal extraction – implemented in both ASM-HEMT and MVSG_CMC parameter flow
 - Trapping extraction – implemented in MVSG_CMC parameter flow
will implement in ASM-HEMT parameter flow soon

Thanks

- Thanks to Prof. Sourabh Khandelwal, developer of ASM-HEMT, for his help in the development of ASM-HEMT parameter flow in IC-CAP
- Thanks to Prof. Lan Wei, developer of MVSG_CMC, for her help in the development of MVSG_CMC parameter flow in IC-CAP

Thank you

Trapping Extraction

Gate Lag Trapping Extraction

Extraction flow

DUTs-Setups Circuit Model Par

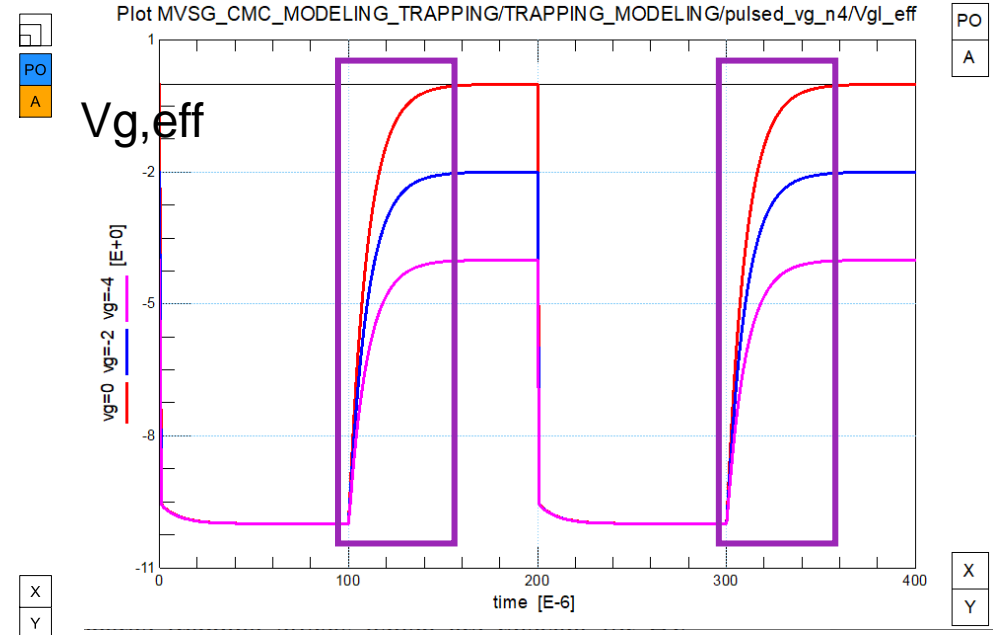
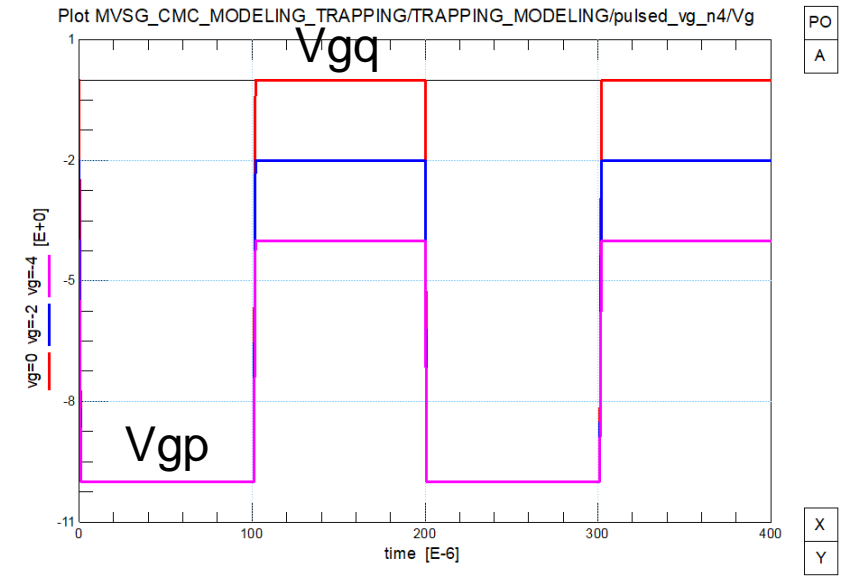
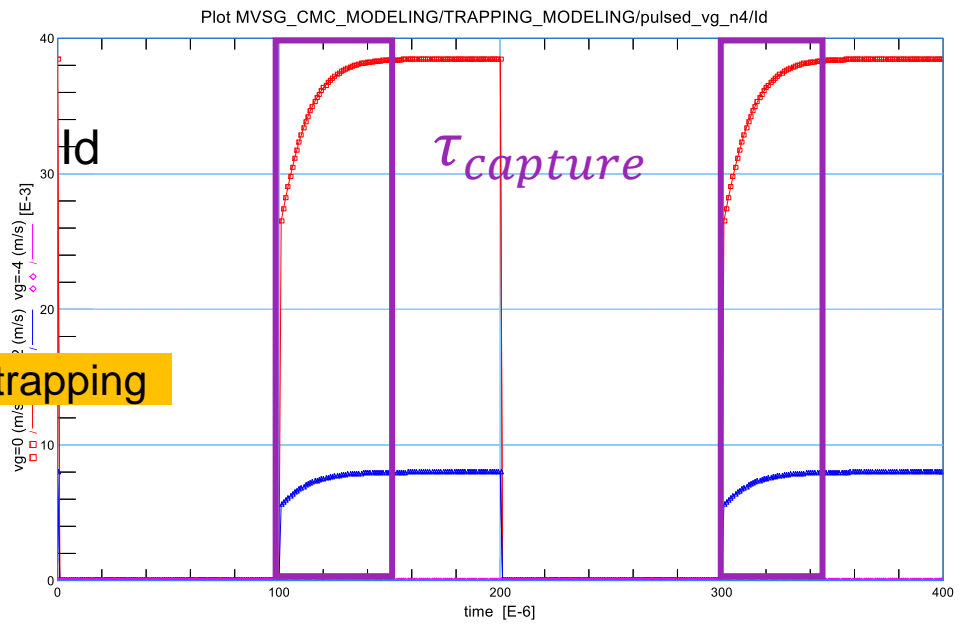
Select DUT/Setup

_DeviceB_2x30_ 0

- INITIALIZE
 - README_FIRST
 - LOAD_MEAS_DATA
 - PROJECT_NAMING
 - DEFINE_WORK_DIR
 - INIT_MODELING
- CONTACT_RESISTANCES 1
- CV_MODELING 2
- DC_MODELING 3
- THERMAL_MODELING_RTH 4
- THERMAL_MODELING_CTH 5
- THERMAL_MODELING_CTH 6
- THERMAL_MODELING_CTH 7
- THERMAL_MODELING_CTH 8
- SPAR_MODELING 9
- TRAPPING_MODELING 10
 - README_FIRST
 - pulsed_vd_50
 - pulsed_vd_40
 - pulsed_vd_30
 - pulsed_vd_20
 - pulsed_vd_10
 - pulsed_vg_0**
 - pulsed_vg_n2**
 - pulsed_vg_n4**
- FINISH_MDLG 11
- _DUTs_below_are_dynamic 12

Gate-Lag trapping

- We select new trapping model with TRAPSELECT=2
- Mainly parameters can be used: rcapture=rslow, remission=rfast, vdltraph



Trapping Extraction

Drain Lag Trapping Extraction

DUTs-Setups Circuit Model Par

Select DUT/Setup

_DeviceB_2x30_ 0

- INITIALIZE
 - README_FIRST
 - LOAD_MEAS_DATA
 - PROJECT_NAMING
 - DEFINE_WORK_DIR
 - INIT_MODELING
- > CONTACT_RESISTANCES 1
- > CV_MODELING 2
- > DC_MODELING 2
- > THERMAL_MODELING 3
- > THERMAL_MODELING_CTH 3
- > THERMAL_MODELING_CTH 3
- > THERMAL_MODELING_CTH 3
- > THERMAL_MODELING_CTH 3
- > SPAR_MODELING 4
- > TRAPPING_MODELING 5
 - README_FIRST
 - pulsed_vd_50**
 - pulsed_vd_40**
 - pulsed_vd_30**
 - pulsed_vd_20**
 - pulsed_vd_10**
 - pulsed_vg_0
 - pulsed_vg_n2
 - pulsed_vg_n4
- > FINISH_MDLG 6
- _DUTs_below_are_dynamic

- We select new trapping model with TRAPSELECT=2
- Mainly parameters can be used: rcapture=rslow, remission=rfast, vgltraph

Extraction flow

Drain-Lag trapping

